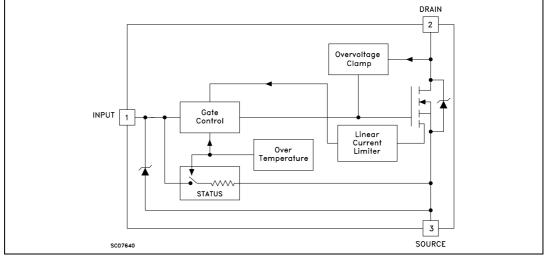
# Contents

1	Block diagram
2	Electrical specification
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	2.3 Electrical characteristics 4
3	Protection features
4	Package information
5	Revision history



# 1 Block diagram







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# 2 Electrical specification

## 2.1 Absolute maximum rating

Table 2. Absolute maximum ra	ting
------------------------------	------

		Value		
Symbol	Parameter	DPAK IPAK	SOT-82FM	Unit
Vds	Drain-source voltage (V <sub>in</sub> = 0)	Internally	clamped	V
Vin	Input voltage	1	8	V
lo	Drain current	Internall	y limited	А
lr	Reverse DC output current	-	7	А
Vesd	Electrostatic discharge (C = 100 pF, R=1.5 K $\Omega$ )	20	00	V
Ptot	Total dissipation at $T_c = 25 $ °C	60	9	W
Tj	Operating junction temperature	Internall	y limited	C
Τc	Case operating temperature	Internall	y limited	°C
Tstg	Storage temperature	-55 to	o 150	°C

### 2.2 Thermal data

Table 3. Thermal data

		DPAK/IPAK	SOT82-FM	
Rthj-case	Thermal resistance junction-case max	3.75	14	C/M
Rthj-amb	Thermal resistance junction-ambient max	100	100	°C/W

### 2.3 Electrical characteristics

### Table 4. Electrical characteristics: off

(-40 < Tj < 125  $^{\circ}$ C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>CLAMP</sub>	Drain-source clamp voltage	I <sub>D</sub> = 200 mA V <sub>in</sub> = 0	32	42	52	V
V <sub>CLTH</sub>	Drain-source clamp threshold voltage	$I_D = 2 \text{ mA } V_{in} = 0$	31	12	02	V
V <sub>INCL</sub>	Input-source reverse clamp voltage	I <sub>in</sub> = -1 mA	-1.1		-0.25	V
I <sub>DSS</sub>	Zero input voltage drain current (V <sub>in</sub> = 0)	$V_{DS} = 13 V V_{in} = 0$ $V_{DS} = 25 V V_{in} = 0$			75 200	μΑ μΑ
I <sub>ISS</sub>	Supply current from input pin	V <sub>DS</sub> = 0 V V <sub>in</sub> = 10 V		250	550	μA

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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>IN(th)</sub>	Input threshold voltage	$V_{DS} = V_{in} I_D + I_{in} = 1 \text{ mA}$	0.8		3	V
		V <sub>in</sub> = 10 V I <sub>D</sub> = 3.5 A			0.14	Ω
		$V_{in} = 10 V I_D = 3.5 A$ $V_{in} = 5 V I_D = 3.5 A$			0.28	Ω
в	Static drain-source on resistance	-40 < T₂ < 25 ℃				
R <sub>DS(on)</sub>		$V_{in} = 10 V I_{D} = 3.5 A$			0.28	Ω
		V <sub>in</sub> = 5 V I <sub>D</sub> = 3.5 A			0.56	Ω
		T <sub>j</sub> = 125 °C				

#### Table 5. **Electrical characteristics: on**

#### Table 6. **Electrical characteristics: dynamic**

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$g_{fs}$ <sup>(1)</sup>	Forward transconductance	V <sub>DS</sub> = 13 V I <sub>D</sub> = 3.5 A	2	5		S
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 13 V f = 1 MHz V <sub>in</sub> = 0		250	500	pF

1. Pulsed: Pulse duration =  $300 \,\mu$ s, duty cycle 1.5 %

Fall time

Turn-on current slope

Total input charge

t<sub>f</sub>

(di/dt)on

Qi

Table 7.	le 7. Electrical characteristics: switching					
Symbol	Parameter	Test conditions	Min.	Тур.		
t <sub>d</sub> (on)	Turn-on delay time	V <sub>DD</sub> = 15 V I <sub>d</sub> = 3.5 A		50		
t <sub>r</sub>	Rise time	$V_{gen} = 10 V R_{gen} = 10 \Omega$		60		
t <sub>d</sub> (off)	Turn-off delay time	(see Figure 26)		130		
t <sub>f</sub>	Fall time			50		
t <sub>d</sub> (on)	Turn-on delay time	V <sub>DD</sub> = 15 V I <sub>d</sub> = 3.5 A		140		
t <sub>r</sub>	Rise time	$V_{gen} = 10 \text{ V R}_{gen} = 1000 \Omega$		0.4		
t <sub>d</sub> (off)	Turn-off delay time	(see Figure 26)		2.5		

 $V_{DD} = 15 \text{ V I}_{D} = 3.5 \text{ A}$ 

 $V_{in}$  = 10 V R<sub>gen</sub> = 10  $\Omega$ 

 $V_{DD} = 12 \text{ V I}_{D} = 3.5 \text{ A V}_{in} = 10 \text{ V}$ 

### T

Table 8.	Electrical	characteristics:	source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub> <sup>(1)</sup>	Forward on voltage	I <sub>SD</sub> = 3.5 A V <sub>in</sub> = 0			1.7	V
t <sub>rr</sub> <sup>(2)</sup>	Reverse recovery time	I <sub>SD</sub> = 3.5 A di/dt = 100 A/µs		40		ns
Q <sub>rr</sub> <sup>(2)</sup>	Reverse recovery charge	$V_{DD} = 30 \text{ V T}_{j} = 25 \text{ C}$		0.2		μC
I <sub>RRM</sub> <sup>(2)</sup>	Reverse recovery current	(see test circuit, Figure 28)		3.6		А

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %

2. Parameters guaranteed by design/characterization



Unit

ns

ns

ns

ns

ns

μs

μs

μs

A/µs

nC

Max. 150

180

300

200

500

1.1

7

4

1

50

18

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>lim</sub>	Drain current limit	V <sub>in</sub> = 10 V V <sub>DS</sub> = 13 V	4	7	11	Α
-11111		$V_{in} = 5 V V_{DS} = 13 V$	4	7	11	A
t <sub>dlim</sub> <sup>(1)</sup>	Step response	V <sub>in</sub> = 10 V		13	20	μs
<sup>L</sup> dlim `´	Current limit	$V_{in} = 5 V$		15	25	μs
T <sub>jsh</sub> <sup>(1)</sup>	Overtemperature shutdown		150			ĉ
T <sub>jrs</sub> <sup>(1)</sup>	Overtemperature reset		135			°C
ı (1)	Foult sink ourront	V <sub>in</sub> = 10 V V <sub>DS</sub> = 13 V		50		mA
$I_{gf}^{(1)}$	Fault sink current	$V_{in} = 5 V V_{DS} = 13 V$		20		mA
E <sub>as</sub> <sup>(1)</sup>	Single pulse avalanche energy	starting T <sub>j</sub> = 25°C V <sub>DD</sub> = 20 V V <sub>in</sub> = 10 V R <sub>gen</sub> = 1 K $\Omega$ L = 30 mH	0.4			J

 Table 9.
 Electrical characteristics: protection

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %

### 3 **Protection features**

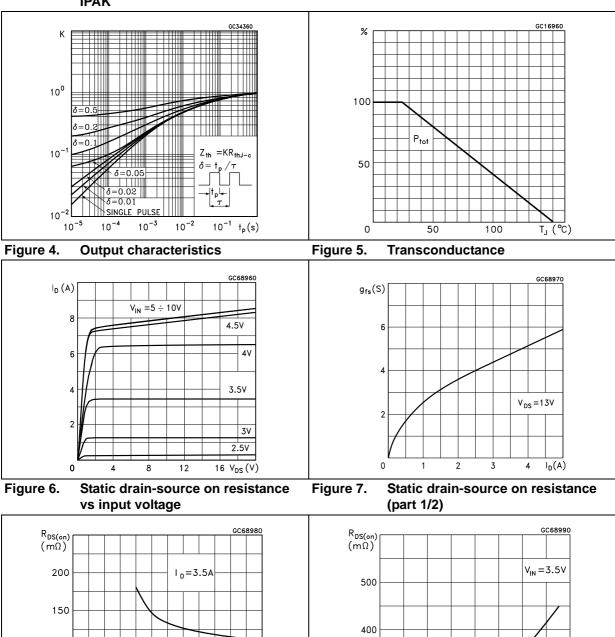
During normal operation, the Input pin is electrically connected to the gate of the internal power MOSFET. The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50 KHz. The only difference from the user's standpoint is that a small DC current (liss) flows into the Input pin in order to supply the internal circuitry.

The device integrates:

- Overvoltage clamp protection: internally set at 42 V, along with the rugged avalanche characteristics of the Power MOSFET stage give this device unrivalled ruggedness and energy handling capability. This feature is mainly important when driving inductive loads.
- Linear current limiter circuit: limits the drain current ld to llim whatever the Input pin voltage. When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the capability of the heatsink. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T<sub>jsh</sub>.
- Overtemperature and short circuit protection: these are based on sensing the chip temperature and are not dependent on the input voltage. The location of the sensing element on the chip in the power stage area ensures fast, accurate detection of the junction temperature. Overtemperature cutout occurs at minimum 150 °C. The device is automatically restarted when the chip temperature falls below 135 °C.
- Status feedback: in the case of an overtemperature fault condition, a Status Feedback is provided through the Input pin. The internal protection circuit disconnects the input from the gate and connects it instead to ground via an equivalent resistance of 100 Ω. The failure can be detected by monitoring the voltage at the Input pin, which will be close to ground potential.

Additional features of this device are ESD protection according to the Human Body model and the ability to be driven from a TTL Logic circuit (with a small increase in RDS(ON)).





300

200 L 0

0.4

0.8

Figure 2. Thermal impedance for DPAK / IPAK

Figure 3. Derating curve

100

50

0

5

2.5

10

7.5

12.5 VIN(V)



 $I_{D}(A)$ 

1.2

R<sub>DS(on)</sub> (mΩ)

180

160

140

120

100

0

### GC69010 $V_{IN}$ (V) 10 8 6 4 $V_{DS} = 15V$ 2 $I_{D} = 3.5A$ 0 5 10 15 20 25 Qg(nC)

Input charge vs input voltage

1 Figure 10. Capacitance variations

 $V_{IN} = 10V$ 

2

Figure 11. Normalized input threshold voltage vs temperature

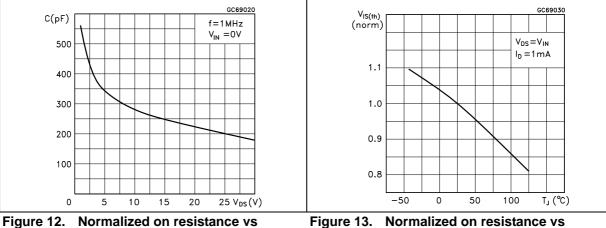


Figure 9.

GC69000

 $I_{D}(A)$ 

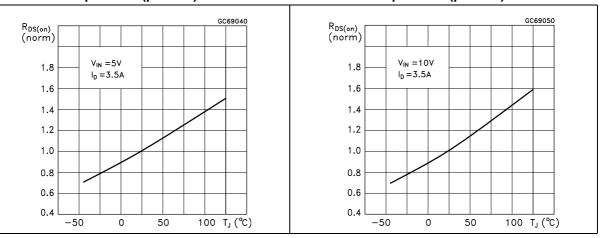
4

 $V_{IN} = 5V$ 

3

temperature (part 1/2)

Figure 13. Normalized on resistance vs temperature (part 2/2)



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GC69070

 $R_{G}(\Omega)$ 

di /dt (A/µ s) di /dt (A/µ s)  $V_{IN} = 5V$ V<sub>IN</sub> =10V 60  $V_{DD} = 15V$  $V_{DD} = 15V$ 60  $I_{D} = 3.5A$  $I_{D} = 3.5A$ 50 50 40 40 30 30 20 20 10 10 200 400 600 800 0 0 200 400 600 800  $R_{G}(\Omega)$ 

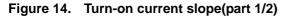


Figure 15. Turn-on current slope(part 2/2)

Figure 16. Turn-off drain-source voltage slope Figure 17. Turn-off drain-source voltage slope (part 1/2) (part 2/2)

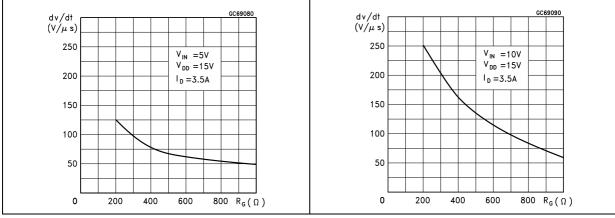
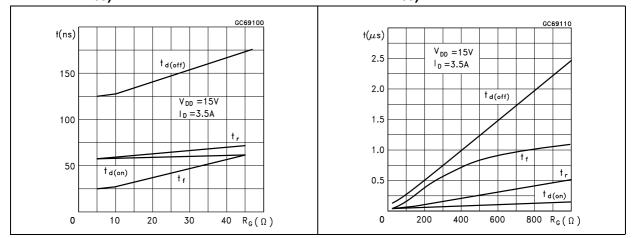


Figure 18. Switching time resistive load (part Figure 19. Switching time resistive load (part 1/3) 2/3)



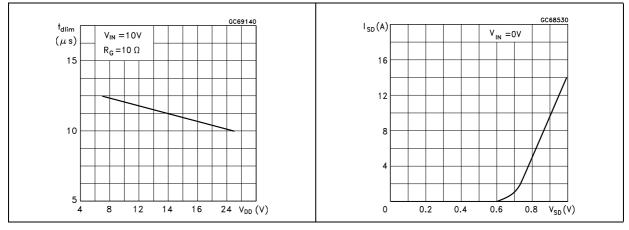


GC69120 GC69130  $I_{lim}(A)$ t(ns)  $V_{DD} = 15V$ 7.6  $I_D = 3.5A$  $R_g = 4.7\Omega$ 175 tr 150  $V_{IN} = 10V$ 7.4 V<sub>DD</sub>=13V 125 t d(off) 100 7.2 75 t<sub>f</sub> 50 7.0 25 t<sub>d(on)</sub> 0 6.8 9  $V_{IN}(V)$ -50 0 50 100 T<sub>J</sub> (℃) 4 5 6 7 8 3

# Figure 20. Switching time resistive load (part Figure 21. Current limit vs junction 3/3) temperature

Figure 22. Step response current limit

Figure 23. Source drain diode forward characteristics

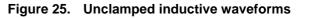




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# Figure 24. Unclamped inductive load test circuits



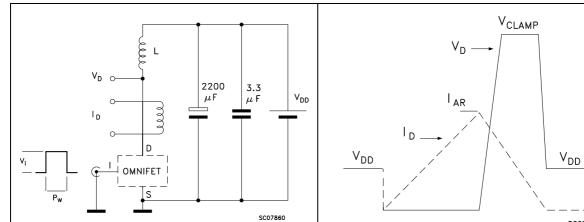
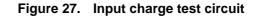
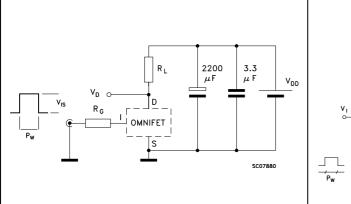


Figure 26. Switching times test circuits for resistive load





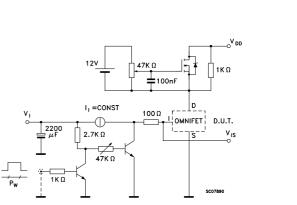
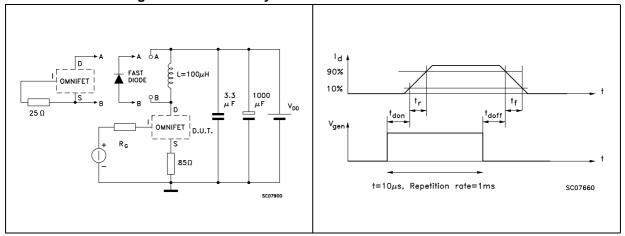


Figure 28. Test circuit for inductive load Figure 29. Waveforms switching and diode recovery times



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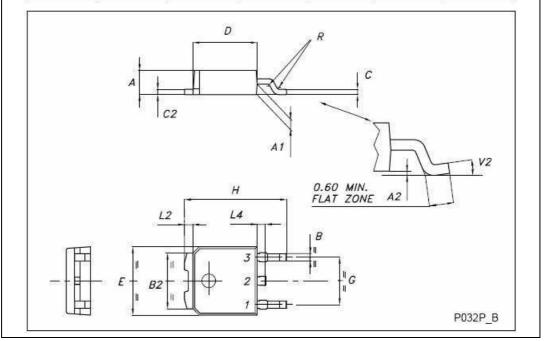
# 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>.

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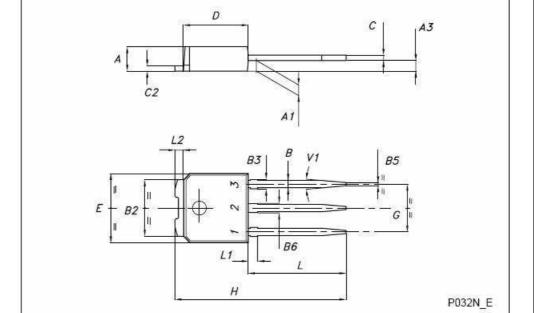
DIM.		mm		inch		
DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03	2	0.23	0.001		0.009
В	0.64		0.90	0.025	2	0.035
B2	5.20		5.40	0.204		0.213
С	0.45	8	0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00	X	6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40	с. С	4.60	0.173		0.181
н	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°	8	8°	0°		0°

Figure 30. TO-252 (DPAK) mechanical data



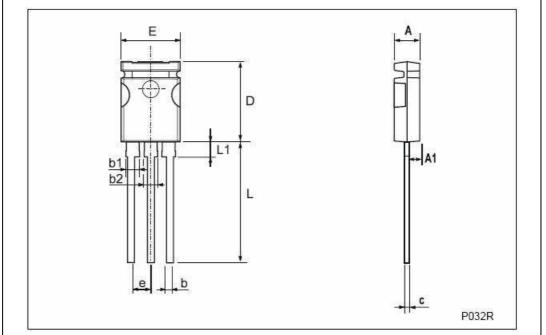
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70		1.30	0.028		0.051
В	0.64		0.90	0.025		0.035
B2	5.20	6	5.40	0.204		0.213
B3			0.85			0.033
B5		0.30	96 9.2		0.012	
B6	с. С.		0.95	l		0.037
С	0.45		0.60	0.018		0.024
C2	0.48	8	0.60	0.019		0.024
D	6.00	9 5	6.20	0.237		0.244
E	6.40		6.60	0.252		0.260
G	4.40	8	4.60	0.173		0.181
Н	15.90	6 X	16.30	0.626		0.642
L	9.00		9.40	0.354		0.370
L1	0.80	2	1.20	0.031		0.047
L2		0.80	1.00	2	0.031	0.039
V1		10°			10°	

Figure 31. TO-251 (IPAK) mechanical data



DIM.		mm		inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX
A	2.85		3.05	1.122		1.200
A1	1.47		1.67	0.578		0.657
b	0.40		0.60	0.157		0.236
b1	1.4		1.6	0.551		0.630
b2	1.3		1.5	0.511		0.590
C	0.45		0.6	0.177		0.236
D	10.5	8. 12	10.9	4.133		4.291
е	2.2		2.8	0.866		1.102
Е	7.45	2	7.75	2.933		3.051
L	15.5		15.9	6.102		6.260
L1	1.95	2	2.35	0.767		0.925







# 5 Revision history

Table 10. Document	revision	history	
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Date	Revision	Changes
21-Jun-2004	0.1	Initial release.
18-Mar-2009	1	Document reformatted. Added <i>Table 1: Device summary on page 1.</i> Updated <i>Section 4: Package information on page 13</i>



# 5 Revision history

Table 10. Document revision	history
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Date	Revision	Changes
21-Jun-2004	1	Initial release.
25-Sep-2013	2	Updated Disclaimer



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